

Product Summary

$V_{(BR)DSS}$	$R_{DS(ON)}$ max	I_D max $T_A = 25^\circ\text{C}$
30V	$21\text{m}\Omega$ @ $V_{GS} = 10\text{V}$	7.3A
	$35\text{m}\Omega$ @ $V_{GS} = 4.5\text{V}$	5.5A

Description and Applications

This MOSFET has been designed to minimize the on-state resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

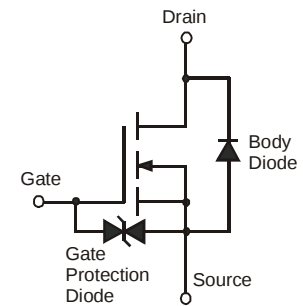
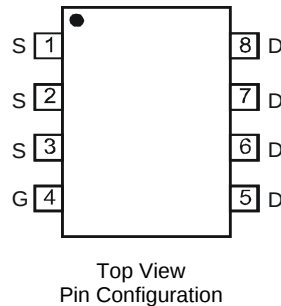
- Backlighting
- Power Management Functions
- DC-DC Converters

Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- **ESD Protected Gate**
- **"Green" component and RoHS compliant (Notes 1 & 2)**
- **Qualified to AEC-Q101 standards for High Reliability**

Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See diagram
- Terminals: Finish — Matte Tin annealed over Copper leadframe.
Solderable per MIL-STD-202, Method 208
- Weight: 0.008 grams (approximate)

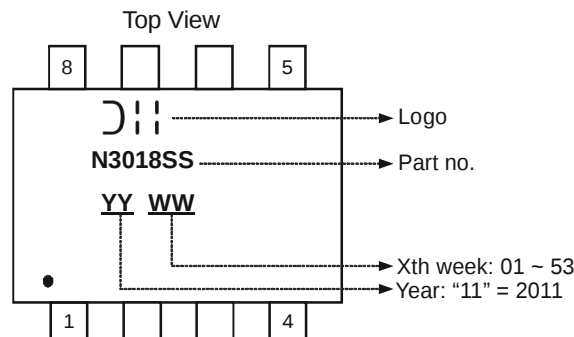


Ordering Information (Note 3)

Part Number	Case	Packaging
DMN3018SSS-13	SO-8	2500/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. No purposely added lead. Halogen and Antimony free.
 2. Diodes Inc.'s "Green" policy can be found on our website at <http://www.diodes.com>.
 3. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information



Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V _{DSS}	30	V
Gate-Source Voltage			V _{GSS}	±25	V
Continuous Drain Current (Note 5) V _{GS} = 10V	Steady State	T _A = 25°C T _A = 70°C	I _D	7.3 5.7	A
	t<10s	T _A = 25°C T _A = 70°C	I _D	9.7 7.8	A
Continuous Drain Current (Note 5) V _{GS} = 4.5V	Steady State	T _A = 25°C T _A = 70°C	I _D	5.5 4.3	A
	t<10s	T _A = 25°C T _A = 70°C	I _D	7.6 5.8	A
Pulsed Drain Current (10μs pulse, duty cycle = 1%)			I _{DM}	60	A
Maximum Body Diode continuous Current			I _S	2.5	A

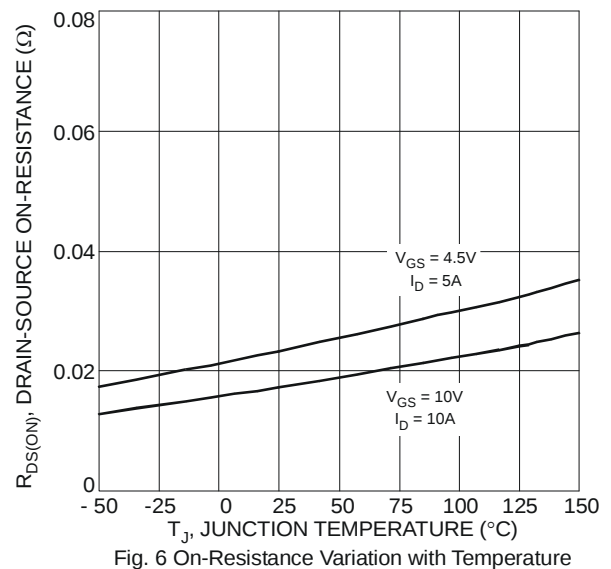
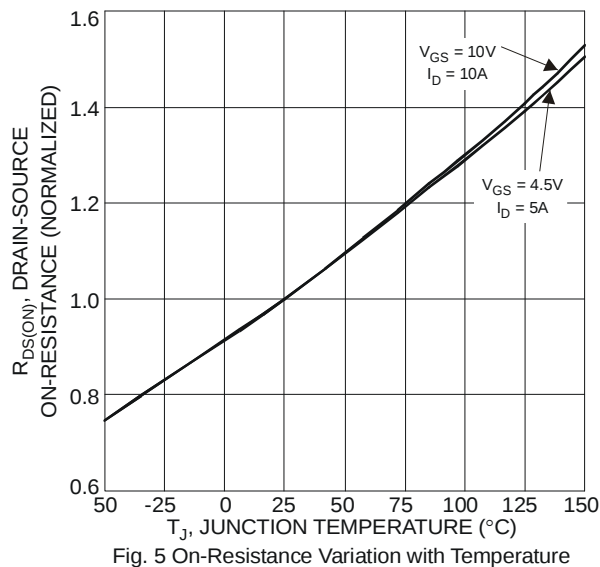
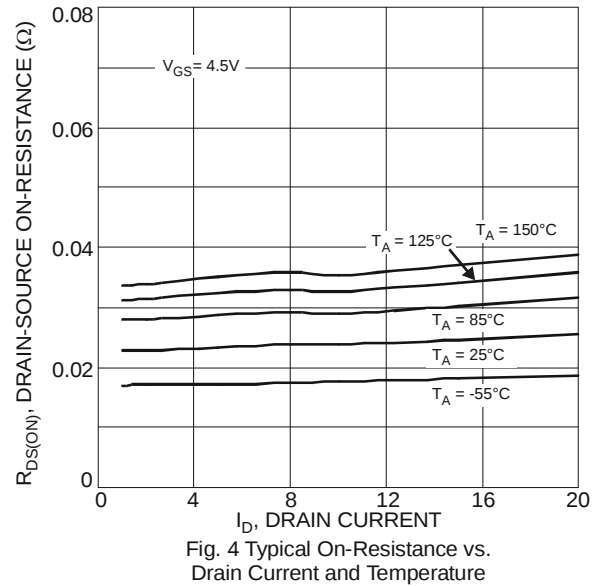
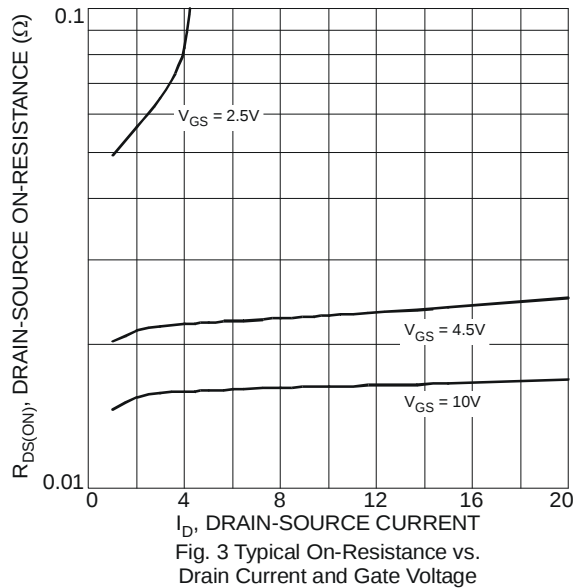
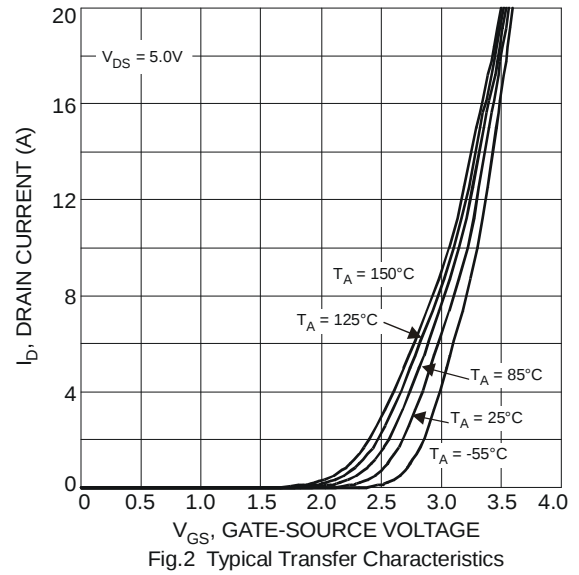
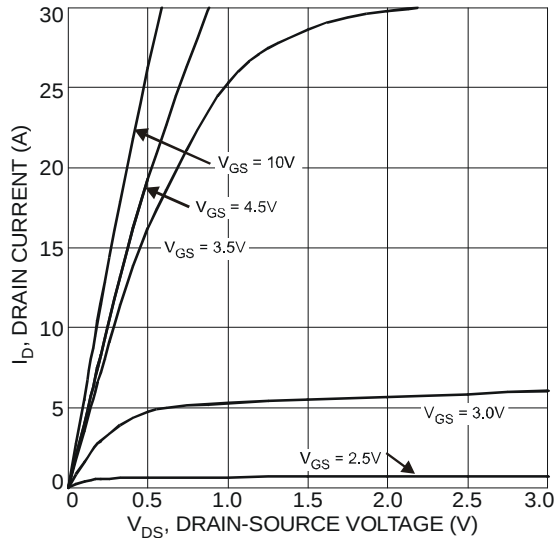
Thermal Characteristics @T_A = 25°C unless otherwise specified

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 4)	T _A = 25°C	P _D	1.4	W
	T _A = 70°C		0.9	
Thermal Resistance, Junction to Ambient (Note 4)	Steady state	R _{θJA}	90	°C/W
	t<10s		50	°C/W
Total Power Dissipation (Note 5)	T _A = 25°C	P _D	1.7	W
	T _A = 70°C		1.1	
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	R _{θJA}	75	°C/W
	t<10s		42	°C/W
Thermal Resistance, Junction to Case (Note 5)		R _{θJC}	7.6	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV _{DSS}	30	-	-	V	V _{GS} = 0V, I _D = 250μA
Zero Gate Voltage Drain Current	I _{DSS}	-	-	1	μA	V _{DS} = 24V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	-	-	±10	μA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	V _{GS(th)}	1	1.7	2.1	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS(on)}	-	15	21	mΩ	V _{GS} = 10V, I _D = 10A
		-	20	35		V _{GS} = 4.5V, I _D = 8.5A
Forward Transfer Admittance	Y _{fs}	-	8.3	-	S	V _{DS} = 5V, I _D = 6.9A
Diode Forward Voltage	V _{SD}	0.5	-	1.2	V	V _{GS} = 0V, I _S = 1A
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	C _{iss}	-	697	-	pF	V _{DS} = 15V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{oss}	-	97	-	pF	
Reverse Transfer Capacitance	C _{rss}	-	67	-	pF	
Gate resistance	R _g	-	1.47	-	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1.0MHz
Total Gate Charge (V _{GS} = 4.5V)	Q _g	-	6.0	-	nC	V _{GS} = 10V, V _{DS} = 15V, I _D = 9A
Total Gate Charge (V _{GS} = 10V)	Q _g	-	13.2	-	nC	
Gate-Source Charge	Q _{gs}	-	2.2	-	nC	
Gate-Drain Charge	Q _{gd}	-	1.8	-	nC	
Turn-On Delay Time	t _{D(on)}	-	4.3	-	ns	V _{DD} = 15V, V _{GS} = 10V, R _L = 15Ω, I _D = 1A, R _G = 6Ω
Turn-On Rise Time	t _r	-	4.4	-	ns	
Turn-Off Delay Time	t _{D(off)}	-	20.1	-	ns	
Turn-Off Fall Time	t _f	-	4.1	-	ns	
Reverse Recovery Time	T _{rr}	-	7.3	-	ns	I _F = 9A, di/dt = 500A/μs
Reverse Recovery Charge	Q _{rr}	-	7.9	-	nC	

- Notes: 4. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
6. Short duration pulse test used to minimize self-heating effect.
7. Guaranteed by design. Not subject to product testing.



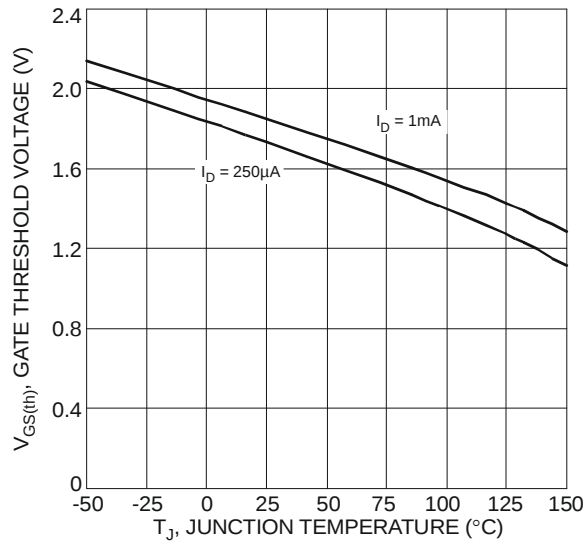


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

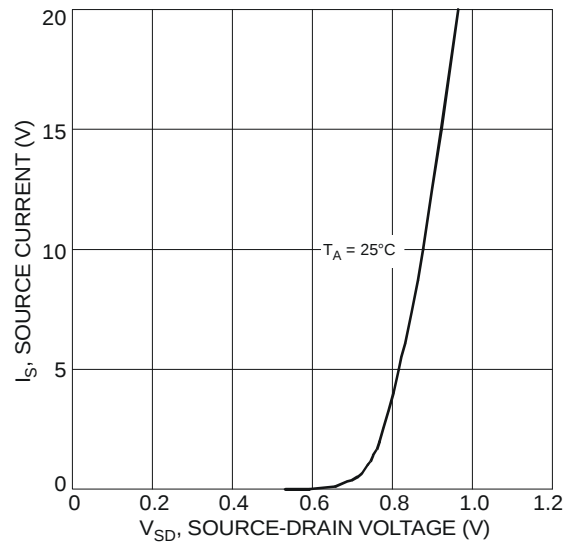


Fig. 8 Diode Forward Voltage vs. Current

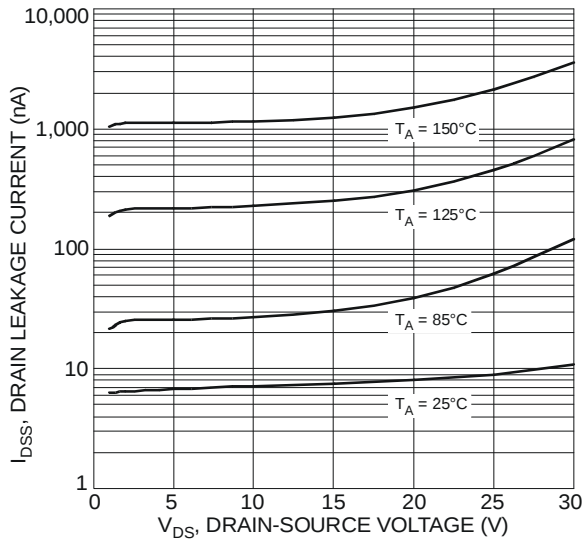


Fig. 9 Typical Drain-Source Leakage Current vs. Voltage

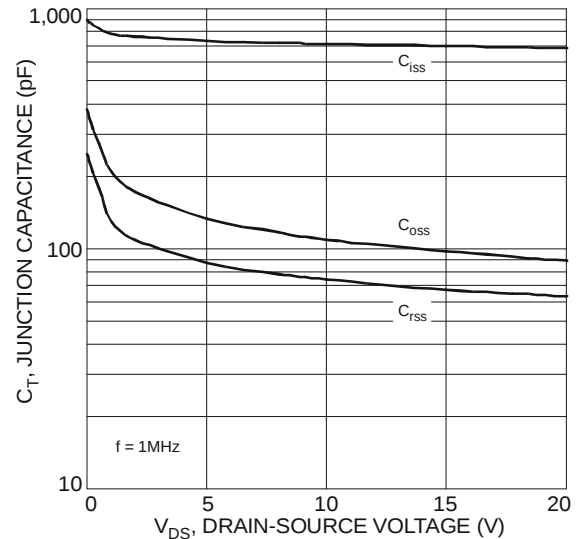


Fig. 10 Typical Junction Capacitance

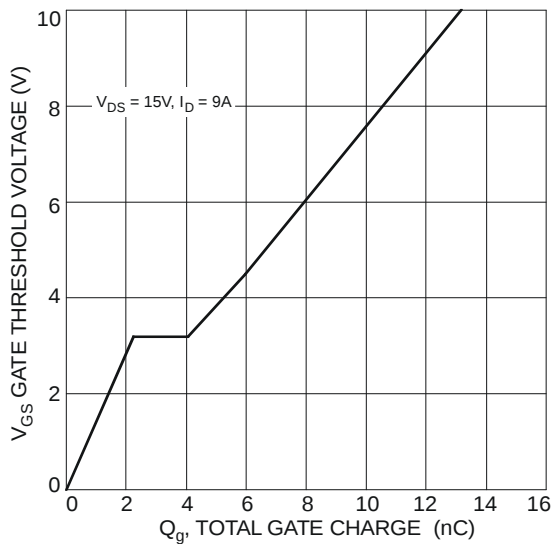
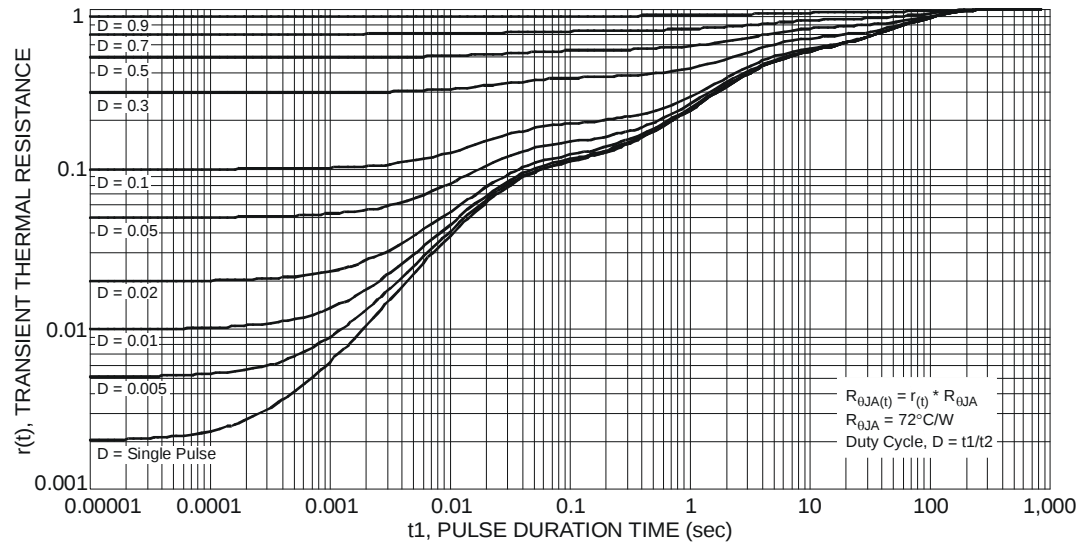
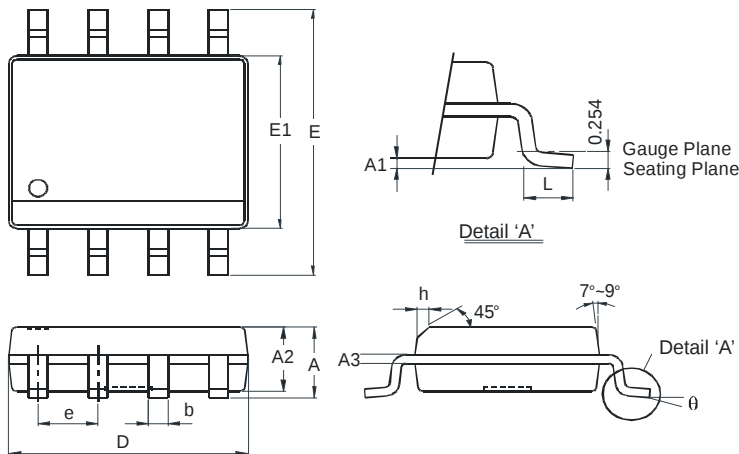


Fig. 11 Gate Charge

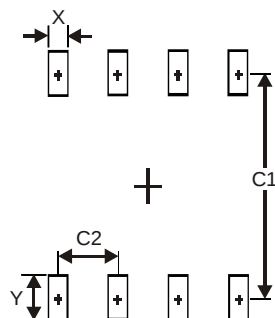


Package Outline Dimensions



SO-8		
Dim	Min	Max
A	-	1.75
A1	0.10	0.20
A2	1.30	1.50
A3	0.15	0.25
b	0.3	0.5
D	4.85	4.95
E	5.90	6.10
E1	3.85	3.95
e	1.27 Typ	
h	-	0.35
L	0.62	0.82
θ	0°	8°
All Dimensions in mm		

Suggested Pad Layout



Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27

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